GSP ～ Automotive Standard Solder Paste ～

Residue Crack Prevention

GSP was developed in collaboration with Toyota, Denso and Denso Ten (Fujitsu Ten). For automotive applications, GSP has excellent electrical and mechanical reliability,even under very severe operating conditions.

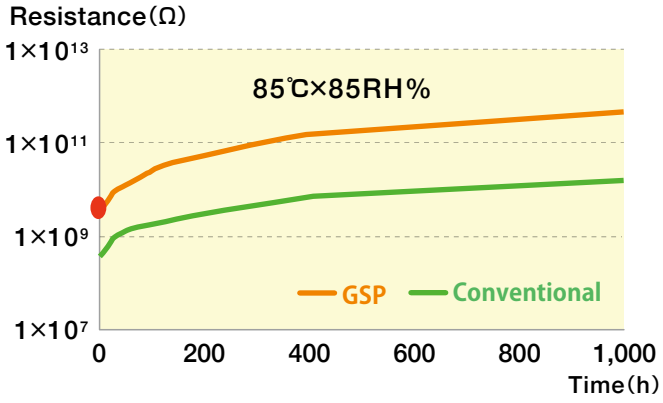
Characteristics

- High insulation resistance value (> 10 (E + 9) Ω) from start to 2,000 hours
- Resistance to flux residue crack (-40⇔+125℃、2,000cycle)
- Stable printing and solderability even after long time continuous printing
- Low solder ball generation even after long time continuous printing

Reliability

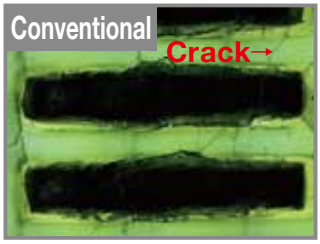
Insulation Resistance Value

- Maintain high insulation resistance from start



Resistance to residue crack(after 2,000)

- No crack flux residue



Evaluation Condition

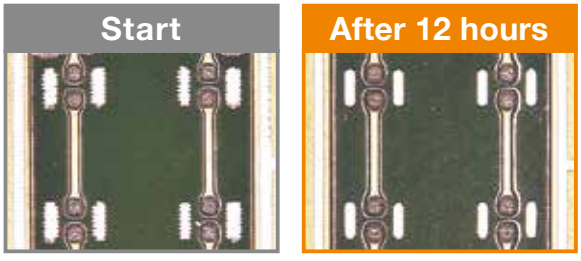
- Cycle Condition :-40⇔+125℃ 30 min
- Observation point :0.5mm Pitch QFP

Observe by lighting from the back of the board

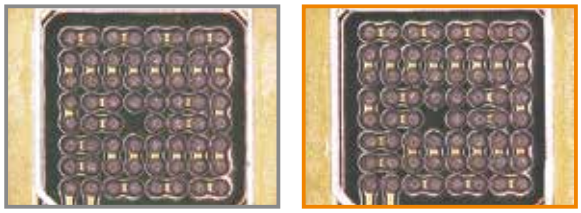
Stability over long time usage

Continuous printing

- Stable printing after prolonged period



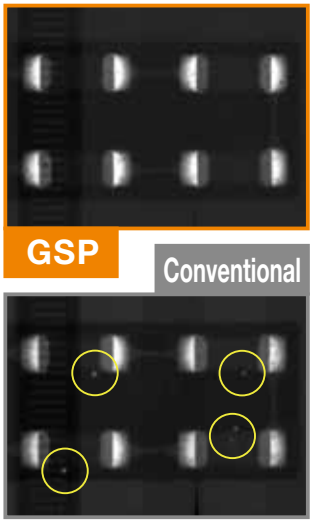
0603 chip



0.5 mm Pitch CSP

Solder ball(after continuous printing)

- Low solder ball even after continuous printing



Evaluation Condition

- After 4 hours continuous printing
- Print/component shift
- Mask thickness 180μ printing